

## High Speed Infrared Emitting Diodes, 850 nm, Surface Emitter Technology

VSMY2850RG



VSMY2850G



### LINKS TO ADDITIONAL RESOURCES



### DESCRIPTION

As part of the [SurfLight™](#) portfolio, the VSMY2850 series are infrared, 850 nm emitting diodes based on GaAlAs surface emitter chip technology with extreme high radiant intensities, high optical power and high speed, m

olded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

### FEATURES

- Package type: surface-mount
- Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.8
- Peak wavelength:  $\lambda_p = 850$  nm
- High reliability
- High radiant power
- Very high radiant intensity
- Angle of half intensity:  $\phi = \pm 10^\circ$
- Suitable for high pulse current operation
- Terminal configurations: gullwing or reverse gullwing
- Package matches with detector VEMD2500X01 series
- Floor life: 4 weeks, MSL 2a, according to J-STD-020
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



### APPLICATIONS

- Miniature light barrier
- Photointerrupters
- Optical switch
- Emitter source for proximity sensors
- IR illumination
- Smart metering

### PRODUCT SUMMARY

| COMPONENT  | $I_e$ (mW/sr) | $\phi$ (°) | $\lambda_p$ (nm) | $t_r$ (ns) |
|------------|---------------|------------|------------------|------------|
| VSMY2850RG | 125           | $\pm 10$   | 850              | 10         |
| VSMY2850G  | 125           | $\pm 10$   | 850              | 10         |

#### Note

- Test conditions see table “Basic Characteristics”

### ORDERING INFORMATION

| ORDERING CODE | PACKAGING     | REMARKS                      | PACKAGE FORM     |
|---------------|---------------|------------------------------|------------------|
| VSMY2850RG    | Tape and reel | MOQ: 6000 pcs, 6000 pcs/reel | Reverse gullwing |
| VSMY2850G     | Tape and reel | MOQ: 6000 pcs, 6000 pcs/reel | Gullwing         |

#### Note

- MOQ: minimum order quantity

**ABSOLUTE MAXIMUM RATINGS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)

| PARAMETER                              | TEST CONDITION                                 | SYMBOL     | VALUE       | UNIT               |
|----------------------------------------|------------------------------------------------|------------|-------------|--------------------|
| Reverse voltage                        |                                                | $V_R$      | 5           | V                  |
| Forward current                        |                                                | $I_F$      | 100         | mA                 |
| Peak forward current                   | $t_p/T = 0.5$ , $t_p = 100\text{ }\mu\text{s}$ | $I_{FM}$   | 200         | mA                 |
| Surge forward current                  | $t_p = 100\text{ }\mu\text{s}$                 | $I_{FSM}$  | 1           | A                  |
| Power dissipation                      |                                                | $P_V$      | 190         | mW                 |
| Junction temperature                   |                                                | $T_j$      | 100         | $^{\circ}\text{C}$ |
| Operating temperature range            |                                                | $T_{amb}$  | -40 to +85  | $^{\circ}\text{C}$ |
| Storage temperature range              |                                                | $T_{stg}$  | -40 to +100 | $^{\circ}\text{C}$ |
| Soldering temperature                  | According to Fig. 10, J-STD-020                | $T_{sd}$   | 260         | $^{\circ}\text{C}$ |
| Thermal resistance junction to ambient | EIA / JESD51                                   | $R_{thJA}$ | 250         | K/W                |

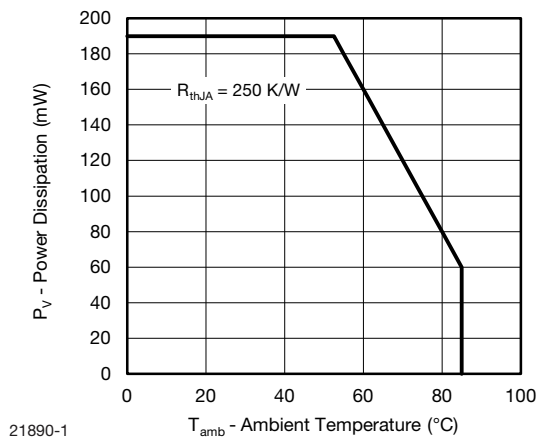


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

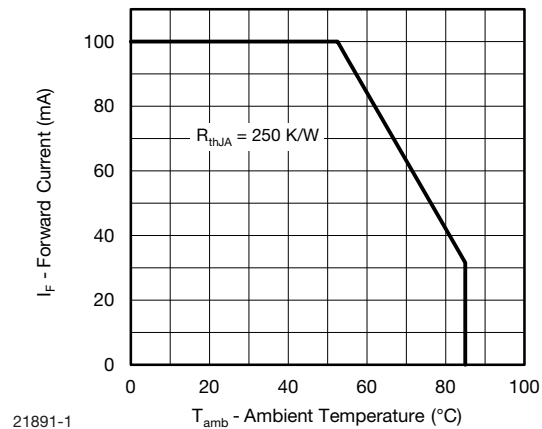


Fig. 2 - Forward Current Limit vs. Ambient Temperature

**BASIC CHARACTERISTICS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)

| PARAMETER                                | TEST CONDITION                                                   | SYMBOL          | MIN.                               | TYP.     | MAX. | UNIT          |
|------------------------------------------|------------------------------------------------------------------|-----------------|------------------------------------|----------|------|---------------|
| Forward voltage                          | $I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$                     | $V_F$           | -                                  | 1.6      | 1.9  | V             |
|                                          | $I_F = 1\text{ A}$ , $t_p = 100\text{ }\mu\text{s}$              | $V_F$           | -                                  | 2.8      | -    | V             |
| Temperature coefficient of $V_F$         | $I_F = 100\text{ mA}$                                            | $TK_{VF}$       | -                                  | -1.5     | -    | mV/K          |
| Reverse current                          |                                                                  | $I_R$           | Not designed for reverse operation |          |      | $\mu\text{A}$ |
| Junction capacitance                     | $V_R = 0\text{ V}$ , $f = 1\text{ MHz}$ , $E = 0\text{ mW/cm}^2$ | $C_J$           | -                                  | 50       | -    | pF            |
| Radiant intensity                        | $I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$                     | $I_e$           | 70                                 | 125      | 210  | mW/sr         |
|                                          | $I_F = 1\text{ A}$ , $t_p = 100\text{ }\mu\text{s}$              | $I_e$           | -                                  | 1000     | -    | mW/sr         |
| Radiant power                            | $I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$                     | $\phi_e$        | -                                  | 55       | -    | mW            |
| Temperature coefficient of radiant power | $I_F = 100\text{ mA}$                                            | $TK\phi_e$      | -                                  | -0.12    | -    | %/K           |
| Angle of half intensity                  |                                                                  | $\phi$          | -                                  | $\pm 10$ | -    | $^{\circ}$    |
| Peak wavelength                          | $I_F = 100\text{ mA}$                                            | $\lambda_p$     | 840                                | 850      | 870  | nm            |
| Spectral bandwidth                       | $I_F = 30\text{ mA}$                                             | $\Delta\lambda$ | -                                  | 30       | -    | nm            |
| Temperature coefficient of $\lambda_p$   | $I_F = 30\text{ mA}$                                             | $TK\lambda_p$   | -                                  | 0.25     | -    | nm/K          |
| Rise time                                | $I_F = 100\text{ mA}$ , 10 % to 90 %                             | $t_r$           | -                                  | 10       | -    | ns            |
| Fall time                                | $I_F = 100\text{ mA}$ , 10 % to 90 %                             | $t_f$           | -                                  | 10       | -    | ns            |



**BASIC CHARACTERISTICS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)

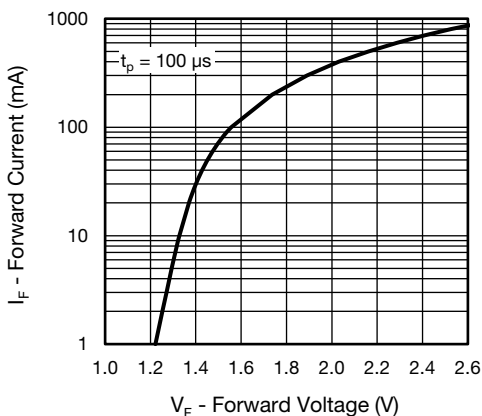


Fig. 3 - Forward Current vs. Forward Voltage

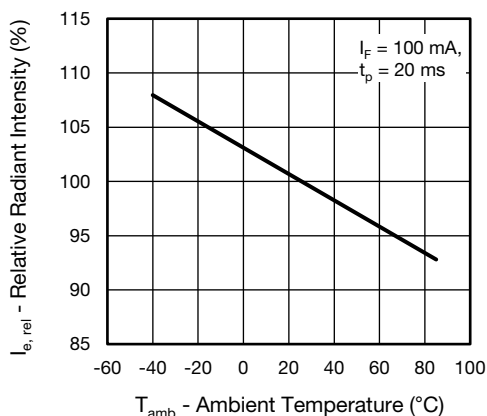


Fig. 6 - Relative Radiant Intensity vs. Ambient Temperature

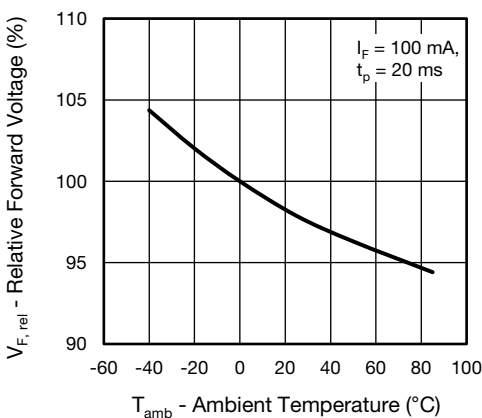


Fig. 4 - Relative Forward Voltage vs. Ambient Temperature

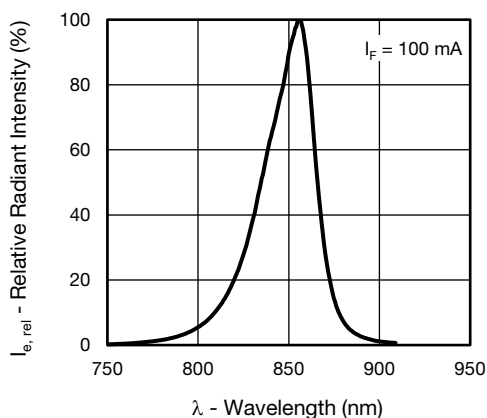


Fig. 7 - Relative Radiant Intensity vs. Wavelength

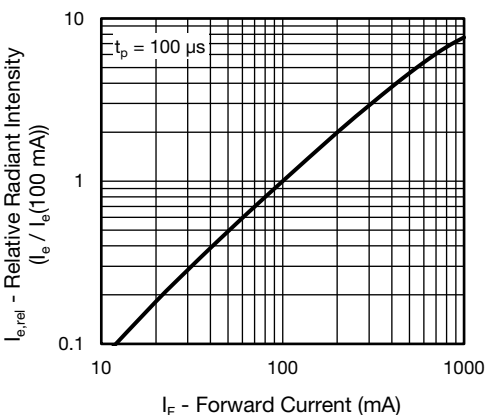


Fig. 5 - Relative Radiant Intensity vs. Forward Current

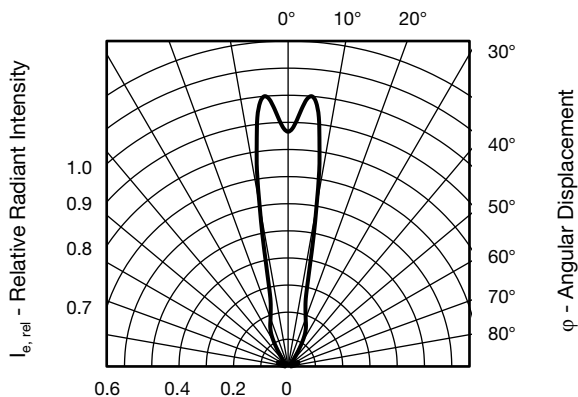
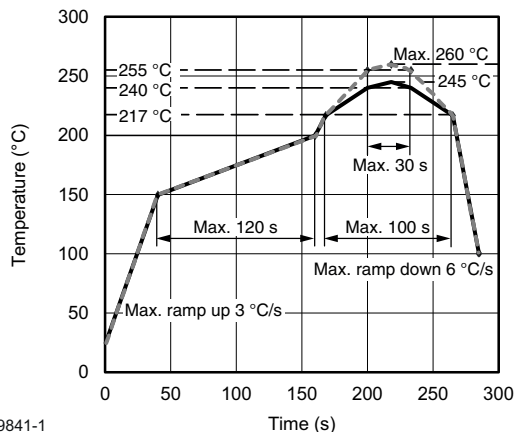


Fig. 8 - Relative Radiant Intensity vs. Angular Displacement



## SOLDER PROFILE



19841-1

Fig. 9 - Lead (Pb)-free Reflow Solder Profile  
According to J-STD-020

## DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

## FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

Conditions:  $T_{amb} < 30\text{ °C}$ ,  $RH < 60\%$

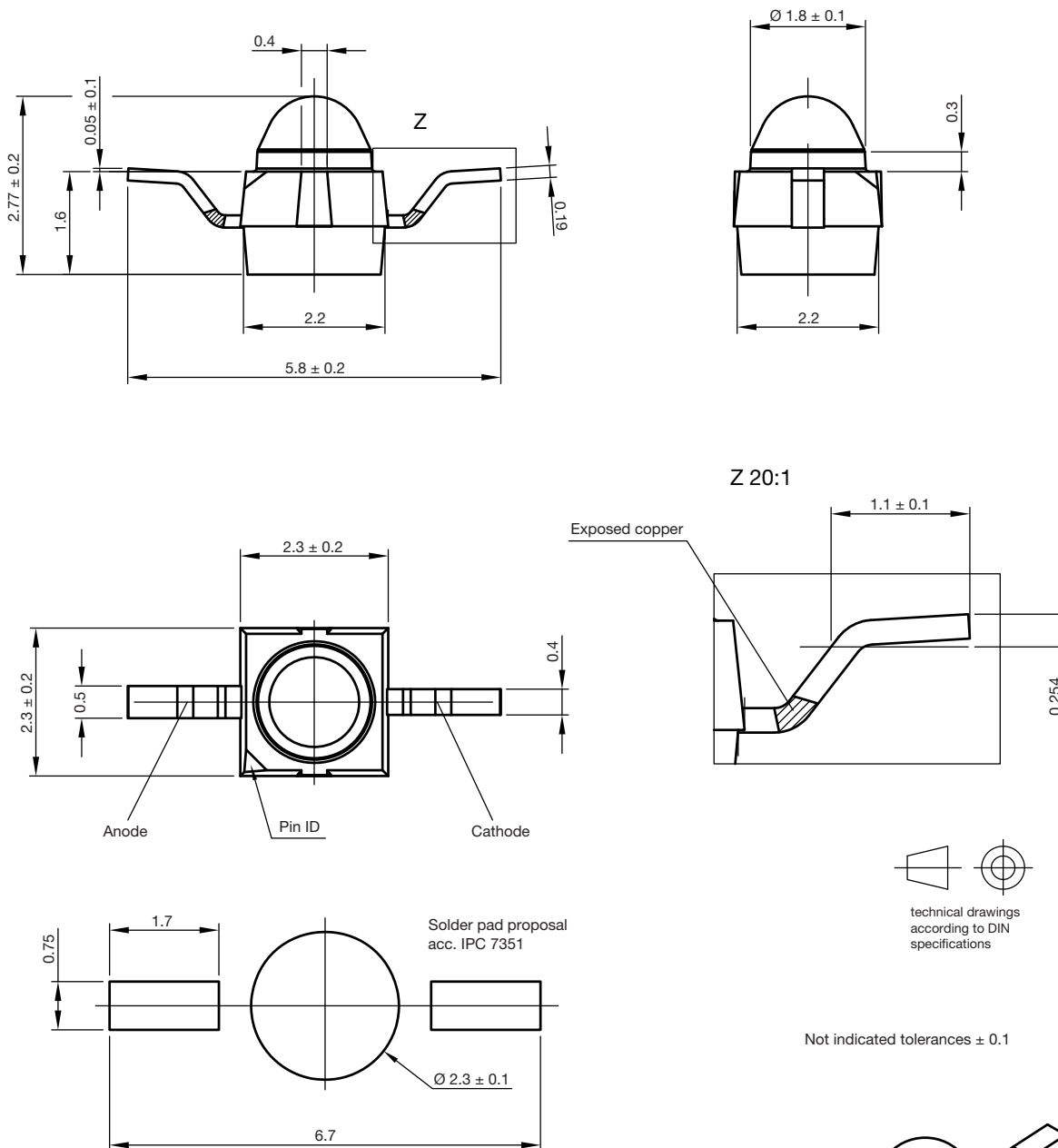
Moisture sensitivity level 2a, according to J-STD-020.

## DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C),  $RH < 5\%$ .



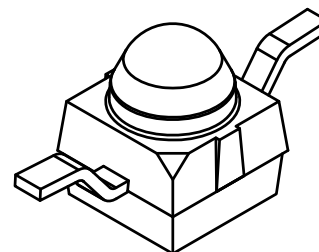
## PACKAGE DIMENSIONS in millimeters: VSMY2850RG



Drawing-No.: 6.544-5391.03-4

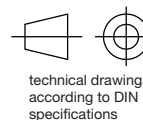
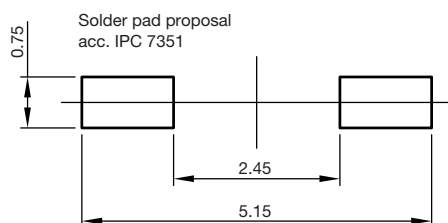
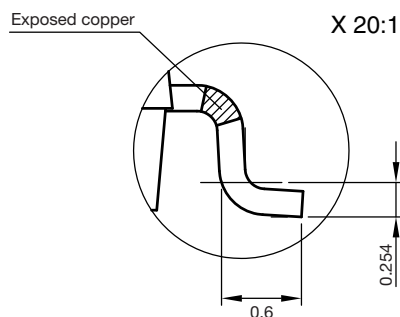
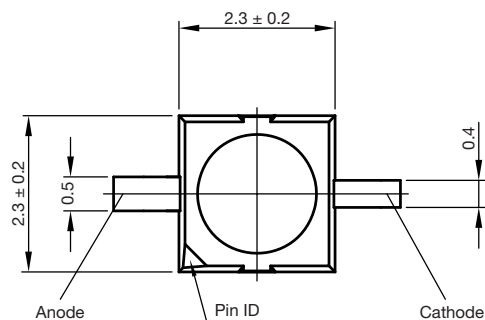
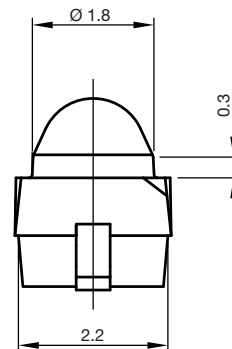
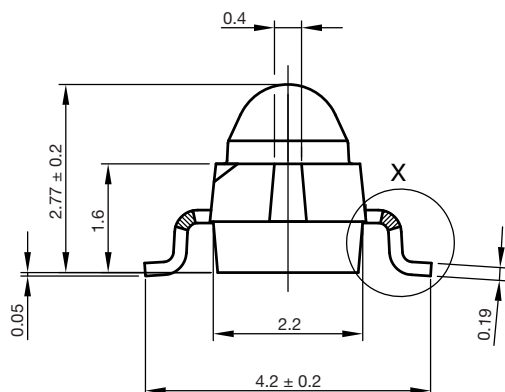
Issue: 1; 18.03.10

22100



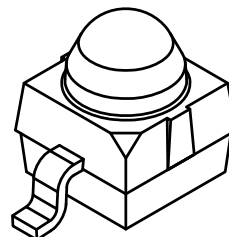


**PACKAGE DIMENSIONS** in millimeters: **VSMY2850G**

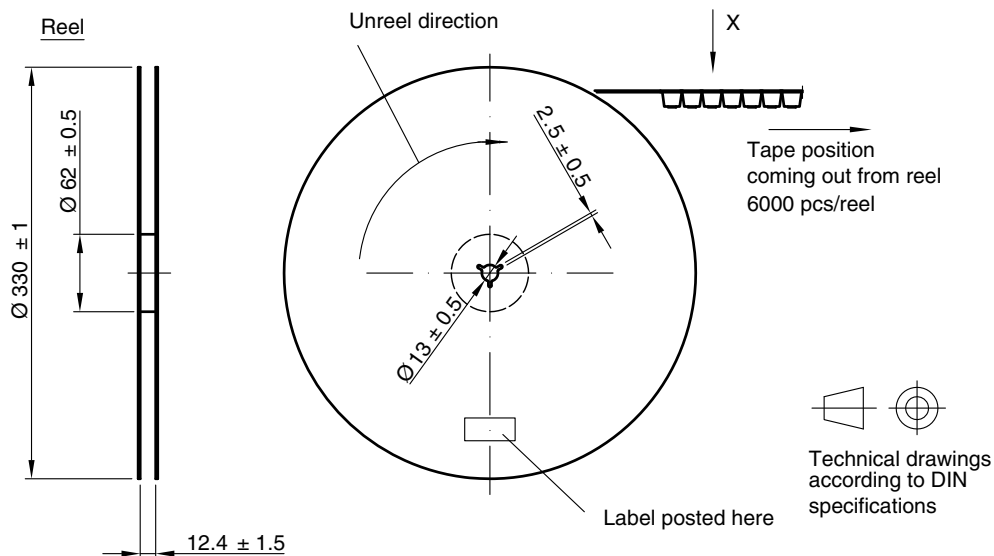


technical drawings  
according to DIN  
specifications

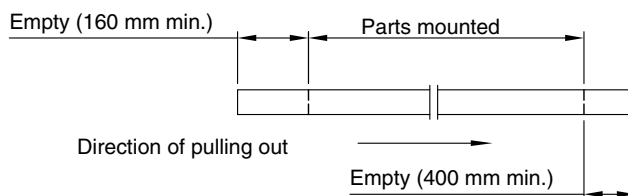
Not indicated tolerances  $\pm 0.1$



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Issue: 1; 18.03.10  
22099

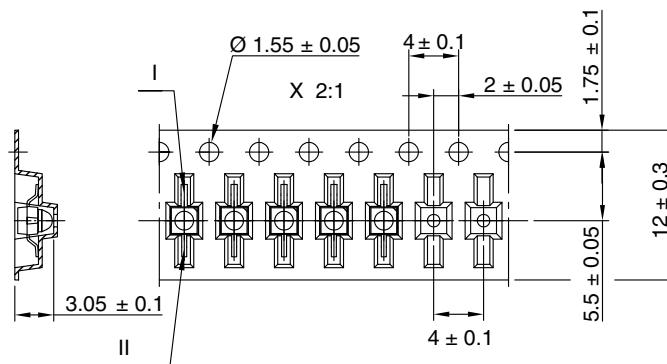
**TAPING AND REEL DIMENSIONS** in millimeters: **VSMY2850RG**


Leader and trailer tape:

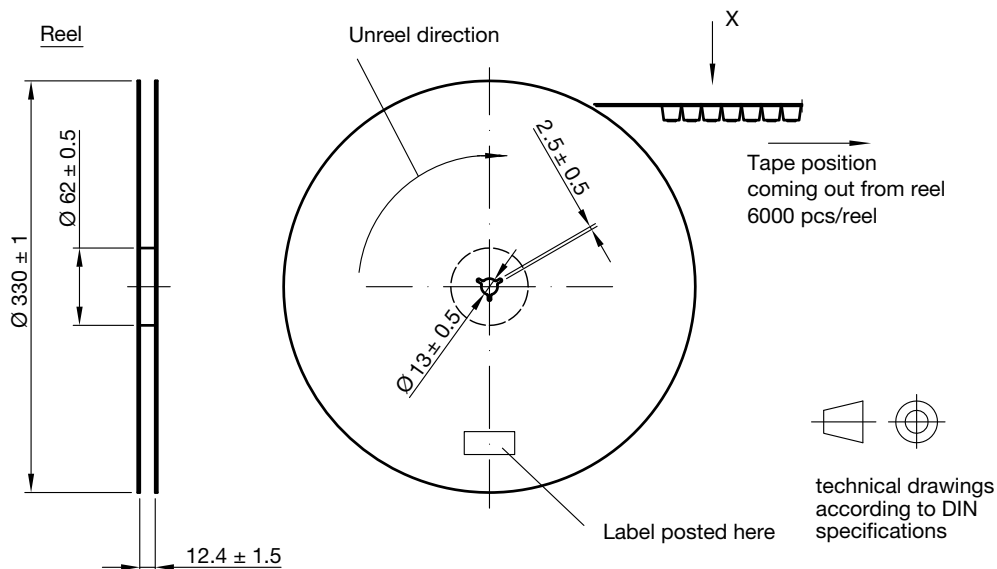
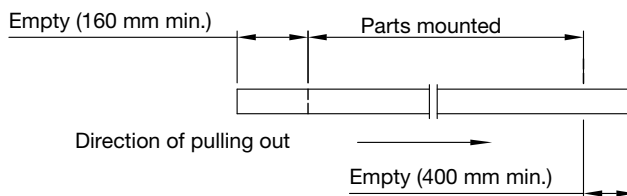


Terminal position in tape

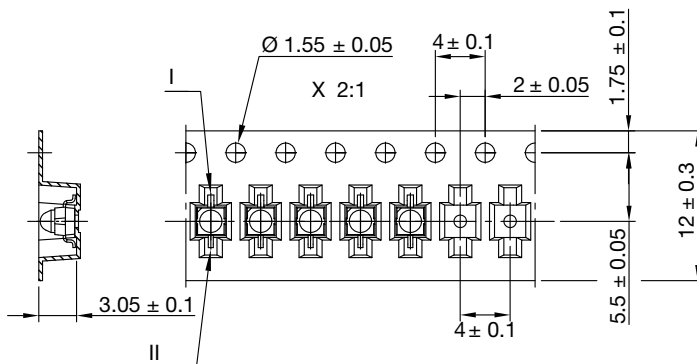
| Device     | Lead I    | Lead II |
|------------|-----------|---------|
| VENT2000   | Collector | Emitter |
| VENT2500   |           |         |
| VEMD2000   | Cathode   | Anode   |
| VEMD2500   |           |         |
| VSMB2000   |           |         |
| VSMG2000   | Anode     | Cathode |
| VSMY2850RG |           |         |



Drawing-No.: 9.800-5100.01-4  
Issue: 2; 18.03.10  
21572

**TAPING AND REEL DIMENSIONS** in millimeters: **VSMY2850G**

**Leader and trailer tape:**

**Terminal position in tape**

| Device       | Lead I    | Lead II |
|--------------|-----------|---------|
| VENT2020     | Collector | Emitter |
| VENT2520     |           |         |
| VSMB2020     | Cathode   | Anode   |
| VSMG2020     |           |         |
| VEMD2020     |           |         |
| VEMD2520     |           |         |
| VSMY2850G    | Anode     | Cathode |
| VSMB294008GC |           |         |



Drawing-No.: 9.800-5091.01-4

Issue: 3; 18.03.10

21571



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